Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current ,per IEC 61000-4-5	$I_{PP_I/O}$	4.7	A	I/O to V_{SS}, 8/20µs
Operating Voltage (DC)	V_{DC}	6	V	V_{CC} to V_{SS}
ESD Protection – Contact Discharge	$V_{ESD_I/O}$	±16	kV	I/O to V_{SS}, per IEC 61000-4-2
	V_{ESD_VCC}	±30	kV	V_{CC} to V_{SS}, per IEC 61000-4-2
ESD Protection – Air Discharge, per IEC 61000-4-2	$V_{ESD_I/O}$	±19	kV	I/O to V_{SS}, per IEC 61000-4-2
	V_{ESD_VCC}	±30	kV	V_{CC} to V_{SS}, per IEC 61000-4-2

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	P_D	200	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	$R_{\theta JA}$	625	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Working Voltage	V_{RWM}	—	—	5.0	V	V_{CC} to V_{SS}
Reverse Current (Note 6)	$I_{R(V_{CC}\ to\ V_{SS})}$	—	—	5.0	µA	$V_R = V_{RWM}$ = 5V, V_{CC} to V_{SS}
Reverse Current (Note 6)	$I_{R(IO\ to\ V_{SS})}$	—	—	1.0	µA	$V_R = V_{RWM}$ = 5V, any I/O to V_{SS}
Reverse Breakdown Voltage	V_{BR}	6.0	—	9.0	V	I_R = 1mA, V_{CC} to V_{SS}
Forward Clamping Voltage	V_F		0.8	1.0	V	I_F = 15mA, V_{SS} to V_{CC}
Reverse Clamping Voltage (Note 7)	$V_{C_I/O}$	—	8.5	—	V	I_{PP} =4.7A, I/O to V_{SS}, 8/20µs
ESD Clamping Voltage	V_{ESD_VCC}	—	10	—	V	TLP, 20A, tp = 100ns, V_{CC} to V_{SS}
	$V_{ESD_I/O}$	—	12	—	V	TLP, 20A, tp = 100ns, I/O to V_{SS}
Dynamic Resistance	R_{DIF_VCC}	—	0.14	—	Ω	TLP, 20A, tp = 100ns, V_{CC} to V_{SS}
	$R_{DIF_I/O}$	—	0.3	—	Ω	TLP, 20A, tp = 100ns, I/O to V_{SS}
Channel Input Capacitance	$C_{I/O\ to\ V_{SS}}$	—	0.55	0.65	pF	V_R = 2.5V, V_{CC} = 5V, f = 1MHz
Channel Input Capacitance	$C_{I/O\ to\ V_{SS}}$	—	0.65	—	pF	V_R = 2.5V, V_{CC} = floating, f = 1MHz
Variation of Channel Input Capacitance	$C_{I/OMAX}$-$C_{I/OMIN}$	—	0.03	—	pF	V_{CC} = 5V, V_{SS} = 0V, I/O = 2.5V, f =1MHz, T = +25°C , $C_{I/OMAX}$ - $C_{I/OMIN}$
Variation of Channel Input Capacitance	$C_{I/OMAX}$-$C_{I/OMIN}$	—	0.05	—	pF	V_{CC} = floating , V_{SS} = 0V, I/O = 2.5V, f = 1MHz, T = +25°C , $C_{I/OMAX}$ - $C_{I/OMIN}$

Notes:
5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.
6. Short duration pulse test used to minimize self-heating effect.
7. Clamping voltage value is based on an 8x20µs peak pulse current (I_{pp}) waveform.

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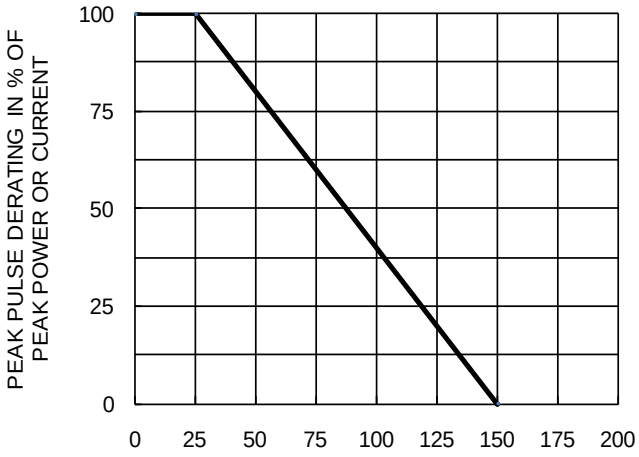
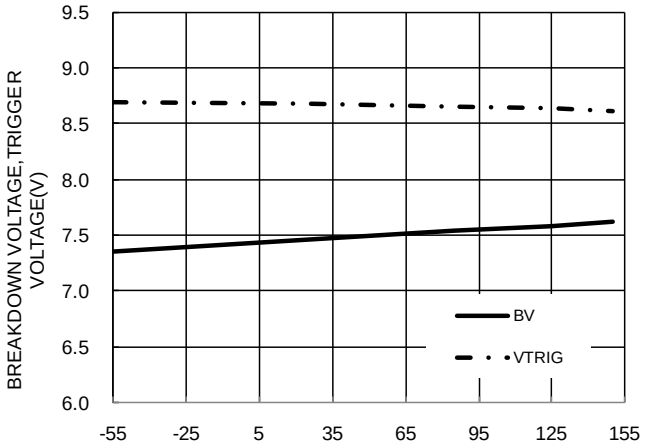
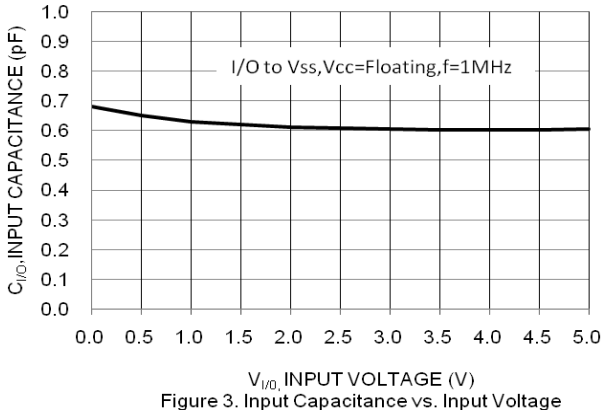


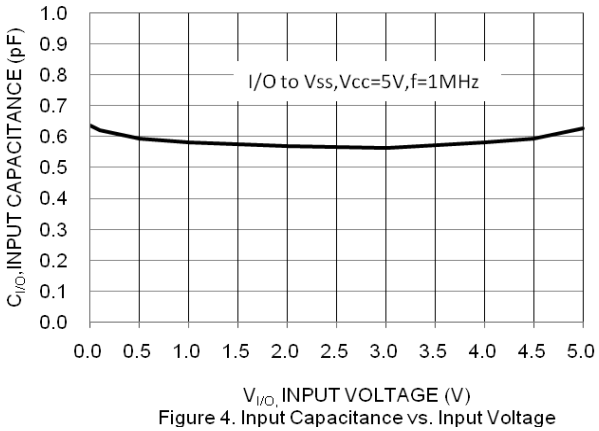
T_A,AMBIENT TEMPERATURE(°C)
Figure1. Pulse Derating Curve



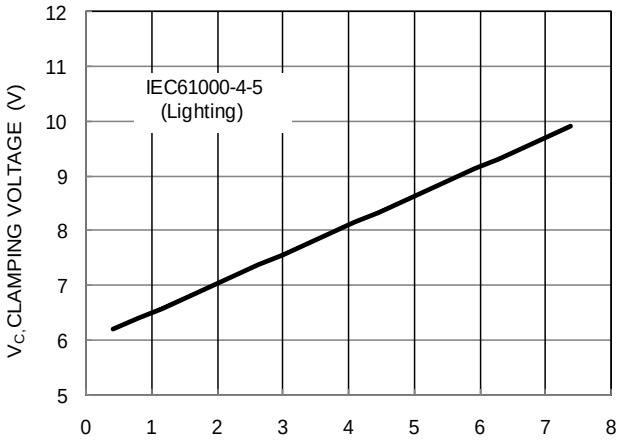
T_A, AMBIENT TEMPERATURE (°C)
Figure 2. BV, Trigger Voltage vs. Ambient Temperature



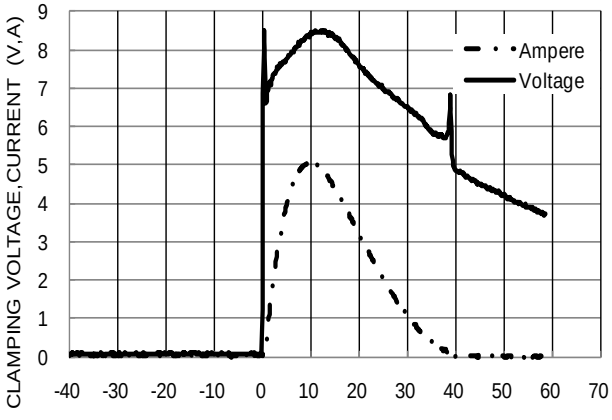
$V_{I/O}$, INPUT VOLTAGE (V)
Figure 3. Input Capacitance vs. Input Voltage



$V_{I/O}$, INPUT VOLTAGE (V)
Figure 4. Input Capacitance vs. Input Voltage



CURRENT FROM I/O TO Vss(A)
Figure 5. Clamping Voltage Characteristic



t,TIME（us）
Figure 6. Waveform of Clamping Voltage,Current vs. Time(8/20us,I/O to Vss)

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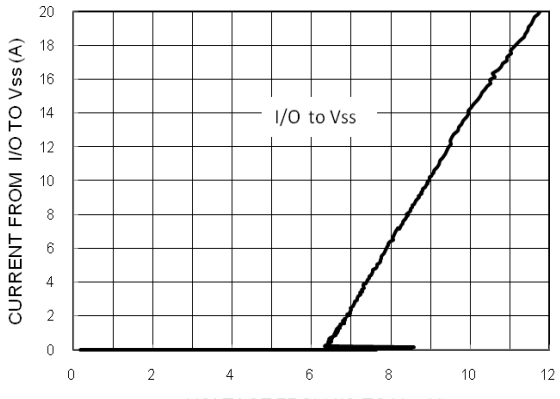


Figure 7. Transmission Line Pulsing (TLP) Measurement Current vs. Voltage

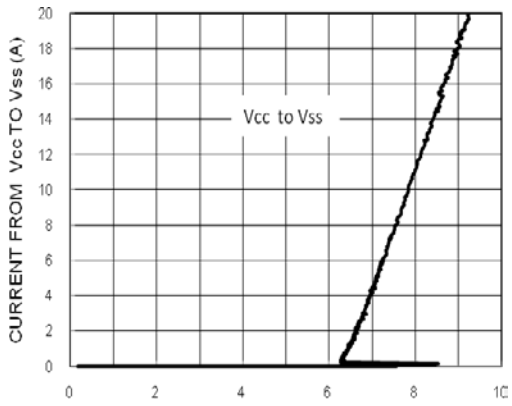
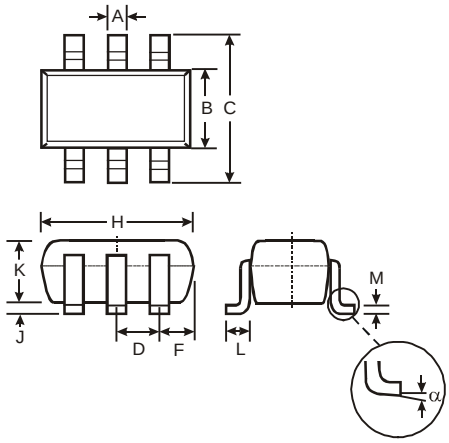


Figure 8. Transmission Line Pulsing (TLP) Measurement Current vs. Voltage

Package Outline Dimensions

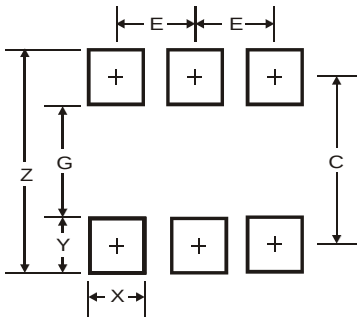
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT363			
Dim	**Min**	**Max**	**Typ**
A	0.10	0.30	0.25
B	1.15	1.35	1.30
C	2.00	2.20	2.10
D	0.65 Typ		
F	0.40	0.45	0.425
H	1.80	2.20	2.15
J	0	0.10	0.05
K	0.90	1.00	1.00
L	0.25	0.40	0.30
M	0.10	0.22	0.11
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C	1.9
E	0.65

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